



MOTOROLA
Semiconductor Products Sector

MECHANICAL OUTLINES
DICTIONARY

98ASS23799W

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DO NOT SCALE THIS DRAWING

ISSUE A

DATE

NOTES

1. DIMENSIONS AND TOLERANCING PER ASME Y14.5M-1994.
2. DIMENSIONS IN MILLIMETERS.
3. DIMENSION b IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM A.
4. PRIMARY DATUM A AND THE SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

DIM	MILLIMETERS		INCHES		DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX		MIN	MAX	MIN	MAX
A	1.45	1.65							
A1	0.60	0.70							
A2	0.85	0.95							
A3	0.25	---							
b	0.65	0.85							
D	37.50	BSC							
D1	35.56	REF							
e	1.27	BSC							
E	37.50	BSC							
E1	35.56	REF							
CASE NO.		1152-01							
STANDARD		JEDEC MO-149 BM-2L							
REFERENCE									
TITLE		480 TBGA, 37.5 X 37.5, 1.27 PITCH							
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